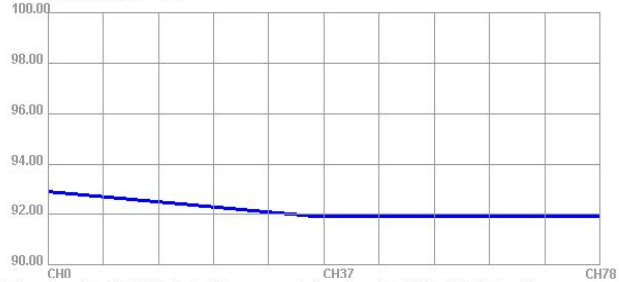


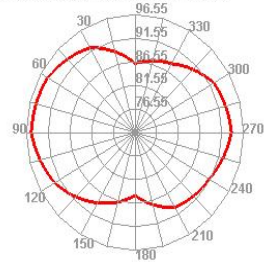
Test Result	Bluetooth TIS		
	0	37	78
Frequency (MHz)	2402	2439	2480
Sens Ave (dBm)	-92.91	-91.95	-91.92
NHPIS (dBm)	NULL	NULL	NULL
RSSIAve	6.35	5.98	5.8
MaxPosRSSI	7.77	8.26	7.73
MaxPosSens	-94.32	-94.23	-93.85
MAX (dBm)	8.88	9.16	8.3
EIS peak	8.88	9.16	8.3
Min (dBm)	-1.7	-2.87	-4.65
Attenuation Horiz	41.22	41.13	41.35
Attenuation Verti	41.09	41.24	41.24

Application Information	
04Version	5.230.336
TotalTime	4m 33s 725ms
AdditionalInfor	25B702097

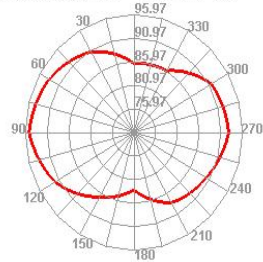
Bluetooth TIS



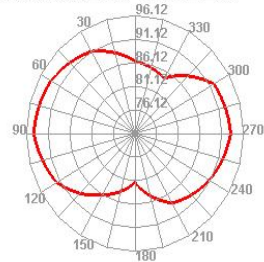
Bluetooth 0 TIS Phi=45



Bluetooth 37 TIS Phi=45



Bluetooth 78 TIS Phi=45

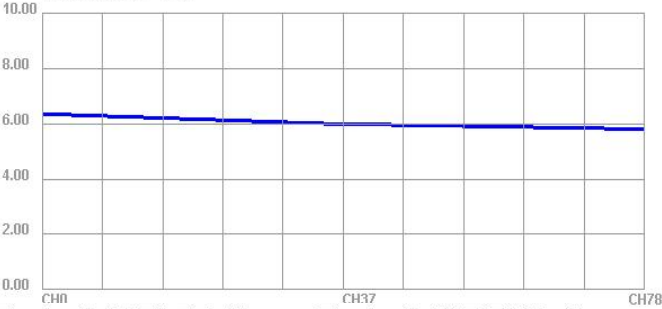


Test Point ID	Freq. (MHz)	Gain (dBi)	Directivity (dBi)	Efficiency (%)
1	2400.0	-0.09	5.35	28.6%
2	2410.0	0.11	5.45	29.3%
3	2420.0	-0.07	5.19	29.8%
4	2430.0	-0.10	4.95	31.3%
5	2440.0	0.31	5.28	31.9%
6	2450.0	0.13	5.05	32.2%
7	2460.0	0.02	5.11	30.9%
8	2470.0	0.07	5.27	30.2%
9	2480.0	0.19	5.23	31.3%
10	2490.0	0.03	5.13	30.9%
11	2500.0	-0.28	5.03	29.4%

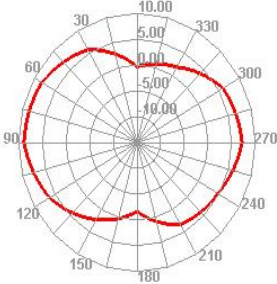
Test Result	Bluetooth TRP		
	0	37	78
Frequency (MHz)	2402	2439	2480
Txp Ave (dBm)	6.35	6	5.8
NHPRP (dBm)	NULL	NULL	NULL
MAX (dBm)	8.88	9.19	8.3
EIRP peak	8.88	9.19	8.3
Min (dBm)	-1.7	-2.84	-4.65
Attenuation Horiz	41.22	41.15	41.35
Attenuation Vertic	41.09	41.27	41.24

Application Information	
04Version	5.230.336
TotalTime	4m 33s 725ms
AdditionalInfor	25B702097

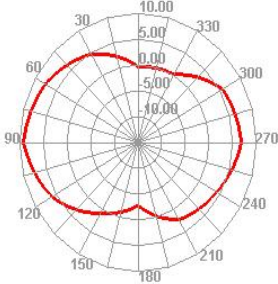
Bluetooth TRP



Bluetooth 0 TRP Phi=45

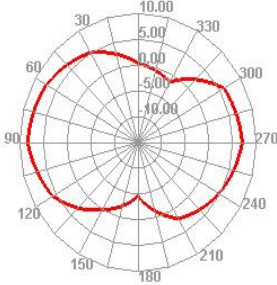


Bluetooth 37 TRP Phi=45

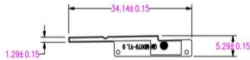


方向图

Bluetooth 78 TRP Phi=45



- 外圈及通孔
- 铜铂
- 基材
- 镀金镀镍
- 离形纸打断线
- 无背胶区
- 背胶区



技术要求:

1. 6层代测的PCB铜板走线部分, 5层代测背胶 9471胶板部分;
2. PCB总厚度为0.13mm, 铜金的厚度为0.01mm/2012;
3. 材料使用单层PI基材, 电铸铜;
4. 油墨为光黑色, 字码为白;
5. PCB来料周边要平整。

尺寸	公差	备注	材料	规格	版本	日期
0-10	±0.02	第三角注	PPC天线	RF	王敏	2025-02-27
10-20	±0.02	第三角注	材料	MD079	RF	2000
20-40	±0.02	第三角注	料号			2024-12-06
40-50	±0.02	第三角注	材料	PI基材+电铸铜	版本	2-A
50-60	±0.02	第三角注				